



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TDFN8 2 mm x 2 mm					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	120	60 000	200 °C + N2	0	0.00
HAST	165	16 500	130 °C, 85 % RH	0	0.00
Pressure Pot	165	15 800	121°, 15 PSIG	0	0.00
Solderability	15	240	883 M2003	0	0.00
Temp. Cycle	165	17 720	- 65 °C to 150 °C	0	0.00